

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"6713789"	USPAT	OR	OFF	2004/12/04 10:36
L2	32	aln with temperature\$4 with sputter\$4	USPAT	OR	OFF	2004/12/04 12:36
L3	5	2 and mocvd	USPAT	OR	OFF	2004/12/04 10:37
L4	5	3 and (sapphire or SiC)	USPAT	OR	OFF	2004/12/04 10:38
L5	1	"4153905".PN.	USPAT; USOCR	OR	OFF	2004/12/04 10:42
L6	1194	aln with temperature\$4	USPAT	OR	OFF	2004/12/04 11:51
L7	53	aln with temperature\$4 with sputter\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/04 12:34
L8	2957	438/22,24,46,48,477,681.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/04 12:35
L9	3587	257/12-14,22,82,85,94.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/04 12:36
L10	6346	8 or 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/04 12:36
L11	4	10 and (aln with temperature\$4 with sputter\$4)	USPAT	OR	OFF	2004/12/04 12:36
L12	5	10 and (aln with temperature\$4 with sputter\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 12:37
L13	724	10 and (group with nitride)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 12:38

L14	389	13 and AlGaN	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 12:39
L15	264	14 and mocvd	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 12:39
L16	253	15 and (sputtering or vapor or evaporation or (ion adj plating) or (laser adj ablation) or ECR)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 12:41
L17	156	16 and AlN	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 12:41
L18	152	17 and temperature\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 12:42
L19	150	18 not 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 13:21
L20	68	19 and sputtering	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 13:39
L21	54	19 and evaporation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 13:50

L22	23	21 not 20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 13:40
L23	16	19 and (ion adj plating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 13:51
L24	16	23 not 22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 13:49
L25	0	24 not 20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 13:51
L26	5	19 and (laser adj ablation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 13:50
L27	0	26 not 20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 13:51
L28	16	19 and ecr	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 13:51
L29	5	28 not 20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 13:51

L30	4	29 not 21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 13:57
L31	4	"6335218"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 14:00
L32	2	"6518599"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 14:01
L33	3	"6541797"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/04 14:01